REMARKS/ARGUMENTS

Favorable reconsideration of this application as currently amended and in light of the following discussion is respectfully requested.

Claims 1-5 are pending, with Claims 1-3 and 5 being presently active in this application, Claim 4 having been previously withdrawn from consideration. By the present amendment, underlining of Claim 5 as previously presented has been removed, and further, Claims 1 and 5 has been presently amended to correct minor informalities.

In the outstanding Office Action Claims 1-3 were rejected under 35 U.S. C. 103(a) as being unpatentable over Spierings (6,045,715) in view of Niwayama (JP-09027469A.

In light of the outstanding rejection, amended Claim 1 clarifies that in the claimed invention the first etching solution removes small defects or micro-cracks from the surfaces of said glass substrates and the second etching solution makes the glass substrates as thin as desirable. Support for the changes to Claim 1 is found at page 7, lines 15-16 if the specification. Claim 5 clarifies that in the claimed method of manufacturing a liquid crystal display device according to Claim 1, --said first etching solution is used at a normal temperature but said second etching solution is used at a higher temperature than the normal temperature--. Support for Claim 5 is found at page 6, lines 8-11 of the specification.

Spierings discloses at column 4, lines 20-22 that "etching rates which are not too high are preferred for patterns for which small dimensional tolerances are required," and at column 5, lines 33-36 states,

> ... For narrow patterns, an etchant which is not too strong is preferably used for the etching treatment.

Therefore, Spierings suggests that the etching rate is slower and etching solution is weaker for removing small defects or micro-cracks.

On the other hand, Niwayama describes "To avoid transferring foreign matter or depositing dust to the surface of a semiconductor substrate" in Japanese 09027469. Furthermore, Niwayama discloses a method for preventing attachment of foreign particles or the like on an oxide and removing the oxide by etching.

Accordingly, from above discussion described, it is respectfully submitted that Claim 1 and its dependent Claims 2, 3 and 5 are patentable Spierings and/or Niwayama.

Consequently, in view of the above comments, the pending claims are believed to be patentably distinguishing over the cited prior art and in condition for allowance. An early and favorable action to that effect is respectfully requested.

Respectfully submitted,

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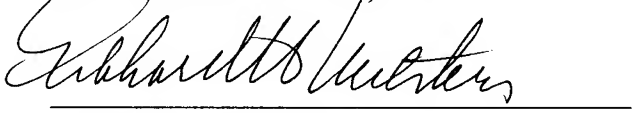

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